

N-Channel Super Junction Power MOSFET $\,\,{\rm IV}$

General Description

(R)

The series of devices use advanced trench gate super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- •Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ●ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

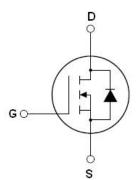
Package Marking And Ordering Information

Device	Device Package	Marking
NCE65NF068D	TO-263	NCE65NF068D

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	45	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	31.5	A
Pulsed drain current ^(Note 1)	DM (pluse)	135	A
Maximum Power Dissipation(Tc=25°C)	PD	371	W
Derate above 25°C		2.47	W/°C
Single pulse avalanche energy ^(Note 2)	Eas	144	mJ
Avalanche current ^(Note 1)	I _{AR}	6	A
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} ^(Note 1)	Ear	0.9	mJ
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V}, I_{SD} \leq I_D$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	TJ,TSTG	-55+175	°C

V_{DS min@Tjmax} 710 V R_{DS(ON)TYP} 60 mΩ ID 45 A Qg 65 nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

TO-263

* limited by maximum junction temperature

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Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.40	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	IDSS	V _{DS} =650V,V _{GS} =0V			300	μA
Gate-Body Leakage Current	Igss	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =500µA	3	4	5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =23A		60	68	mΩ
Dynamic Characteristics						
Input Capacitance	Clss			3900	4400	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V, F=1.0MHz		132		pF
Reverse Transfer Capacitance	C _{rss}			14		pF
Total Gate Charge	Qg			65	70	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =23A, V _{GS} =10V f = 1 MHz open drain		21		nC
Gate-Drain Charge	Q _{gd}			17		nC
Gate plateau voltage	Vgp			6.5		V
Intrinsic gate resistance	R _G			3		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}			42		nS
Turn-on Rise Time	tr	V_{DD} =380V, I_D =23A, R _G =1.7 Ω , V_{GS} =10V		14		nS
Turn-Off Delay Time	t _{d(off)}			90		nS
Turn-Off Fall Time	t _f			12		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	Isd	T _c =25°C			45	А
Pulsed Source-drain current(Body Diode)	Isdm				135	А
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =45A,V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}			173		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=23A,		1.13		uC
Peak Reverse Recovery Current	Irrm	— di/dt=100A/µs —		13		А

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R_G=25Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

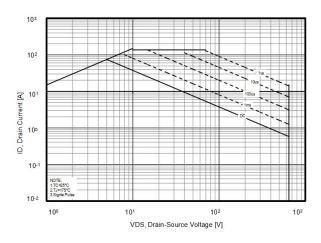
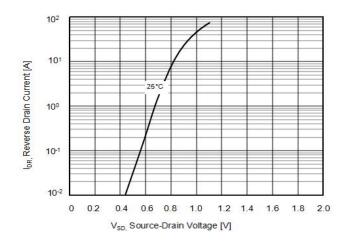
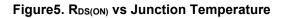


Figure3. Source-Drain Diode Forward Voltage





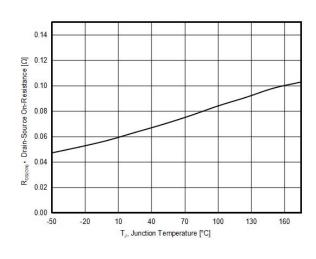


Figure2. Capacitance

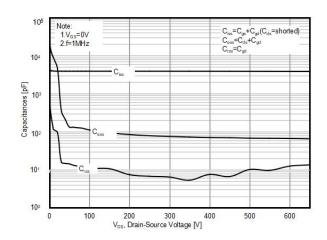


Figure4. Output characteristics

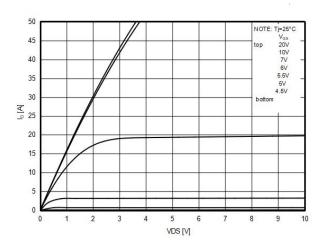
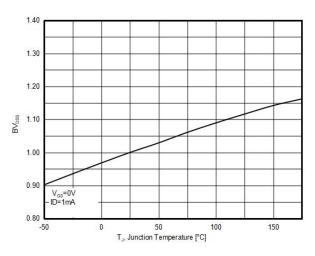


Figure6. BV_{DSS} vs Junction Temperature





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Figure7. Maximum I_D vs Junction Temperature

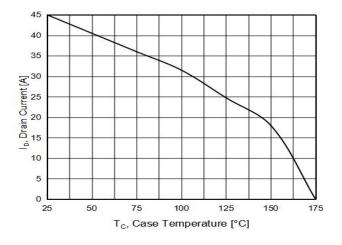


Figure9. Static drain-source on resistance

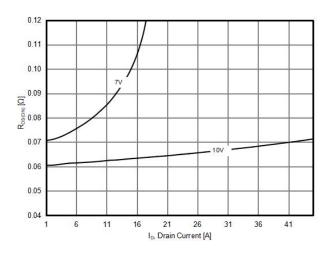


Figure8. Gate charge waveforms

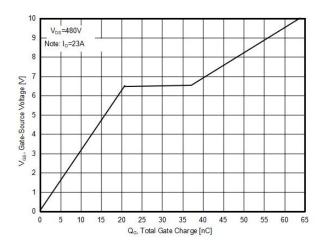
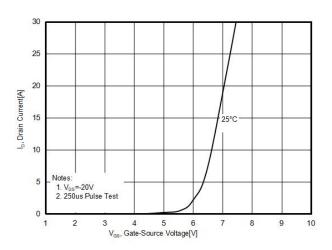


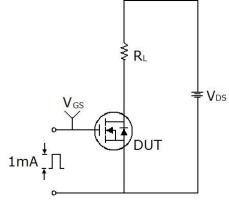
Figure10. Transfer characteristics

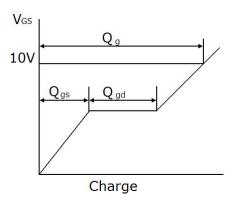




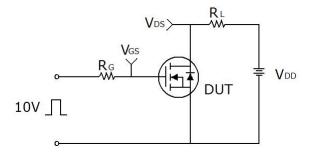
Test circuit

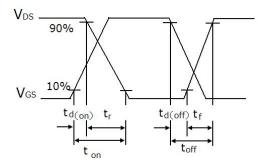
1) Gate charge test circuit & Waveform



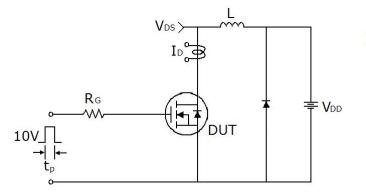


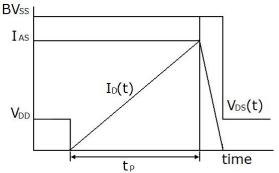
2) Switch Time Test Circuit:





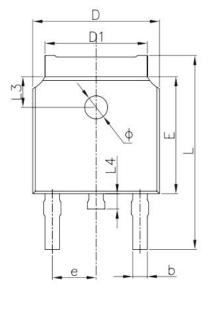
3) Unclamped Inductive Switching Test Circuit & Waveforms

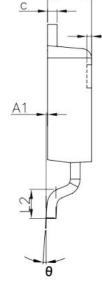




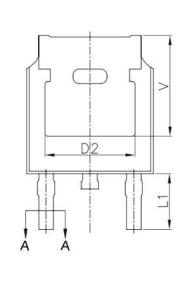


TO-263 (E) Package Information





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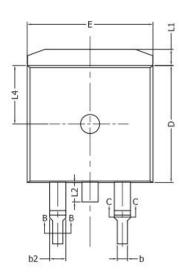


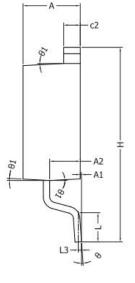
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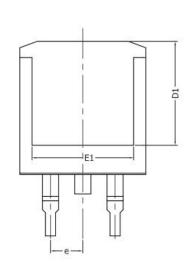
Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	4.20	4.60	0.165	0.181	
A1	-	0.25	-	0.010	
A2	2.20	2.60	0.087	0.102	
b	0.70	0.90	0.028	0.035	
b2	1.17	1.37	0.046	0.054	
С	0.40	0.60	0.016	0.024	
c1	1.15	1.40	0.045	0.055	
D	9.10	9.30	0.358	0.366	
D1	7.63	8.23	0.300	0.324	
E	10.05	10.45	0.396	0.411	
E1	8.35	8.95	0.329	0.352	
е	2.54	2.54 BSC		BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	1.36REF		0.053REF		
L2	1.3REF		0.051REF		
L3	0.25REF		0.009REF		



TO-263 (P) Package Information







Symbol Dimensions In M		Dimensions In Millimeters		ns In Inches	
	Min.	Max.	Min.	Max.	
А	4.40	4.60	0.17	0.18	
A1	0.00	0.25	0.00	0.01	
A2	2.20	2.60	0.09	0.10	
b	0.76	0.89	0.03	0.04	
b2	1.23	1.37	0.05	0.05	
С	0.47	0.60	0.02	0.02	
c2	1.25	1.35	0.05	0.05	
D	9.10	9.30	0.36	0.37	
E	9.80	10.00	0.39	0.39	
Н	14.90	15.70	0.59	0.62	
L	2.00	2.60	0.08	0.10	
L1	1.17	1.40	0.05	0.06	
L2		1.75		0.07	
L3	0.25BSC		0.01BSC		
L4	4.60REF		0.18REF		
θ	0°	8°	0°	8°	
θ1	1°	5°	1°	5°	



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